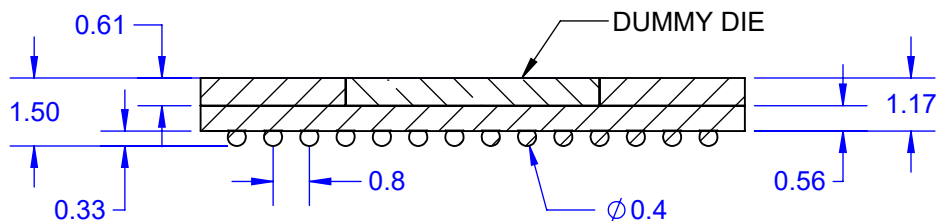
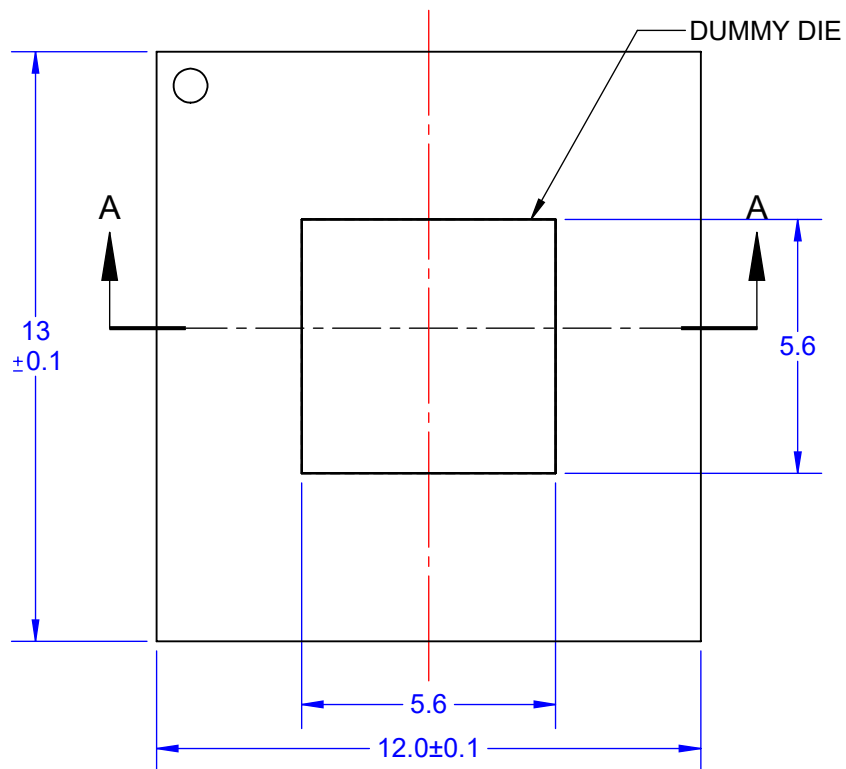
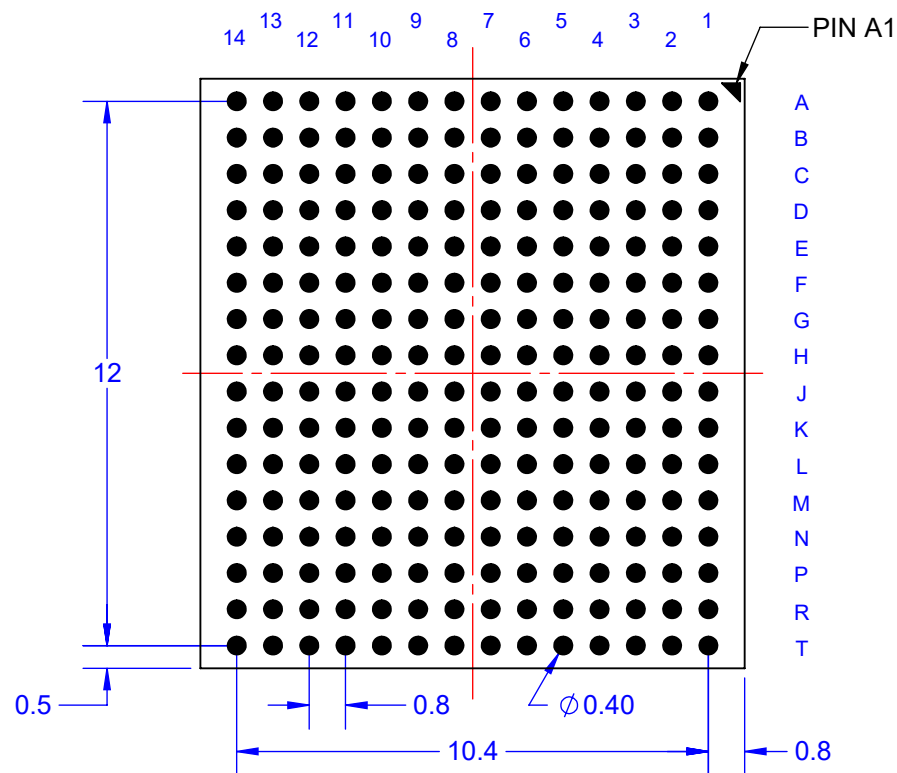


TOP VIEW



SECTION A-A
SCALE 6 : 1

BALL VIEW




Notes: (Unless Otherwise Specified).

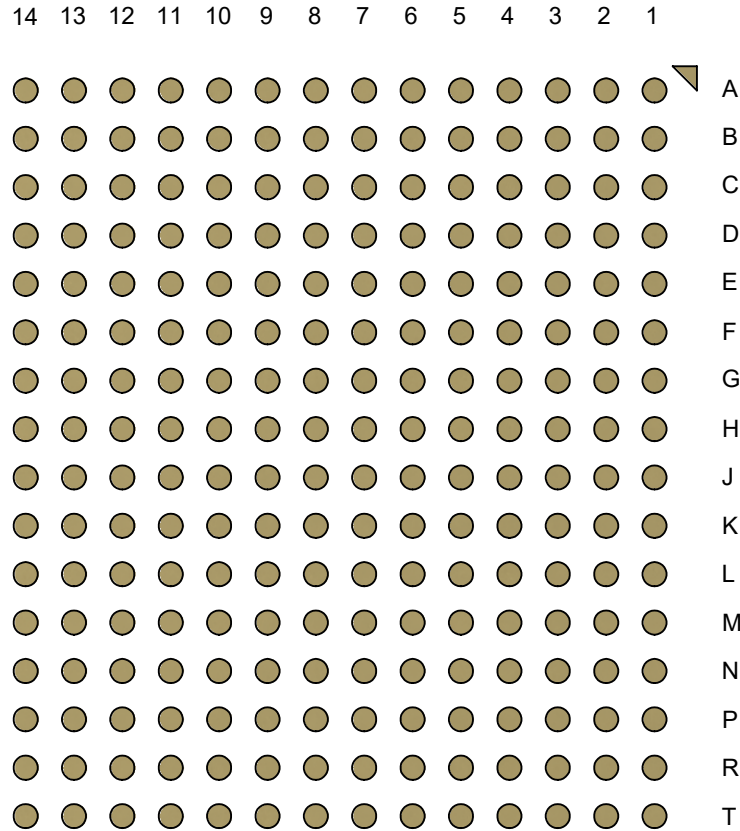
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): $\phi 0.40$ mm (16mil).
- 4) SOLDER MASK DEFINED PAD OPENING: $\phi 0.33$ mm (13mil).
- 5) PAD Cu DIAMETER: $\phi 0.40$ mm (16mil).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN ATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

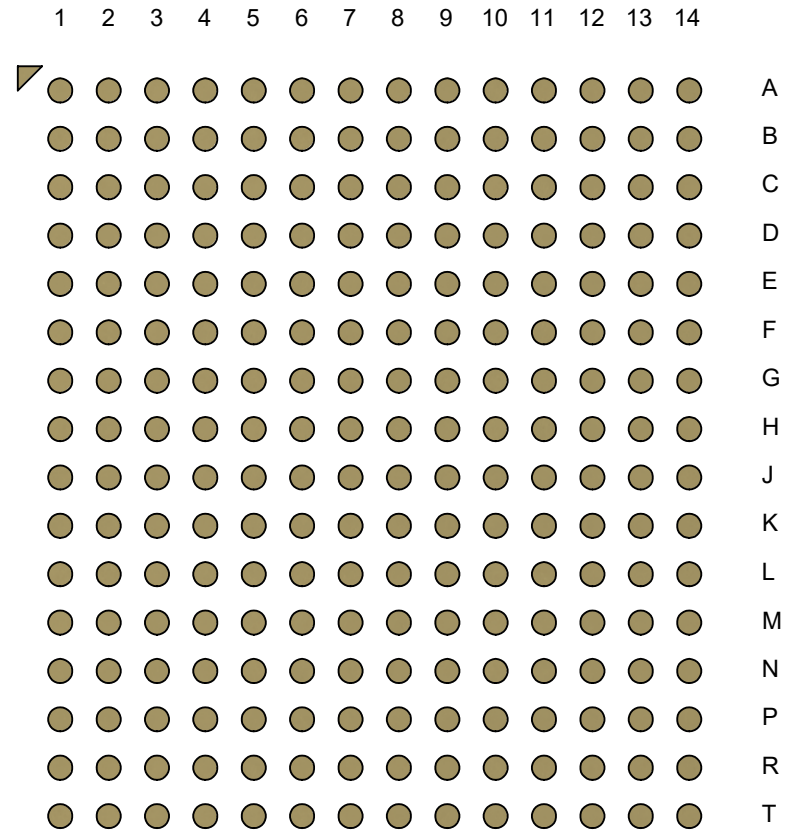
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA224T.8C-14x16-D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA224T.8-14x16-D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T. Au	4/29/2022				
ENG M. Hart	4/29/2022	TITLE BGA224T.8C-14x16-D DUMMY BGA			
MFG		SCALE 6:1	SIZE A	DRAWING NO. 589141	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



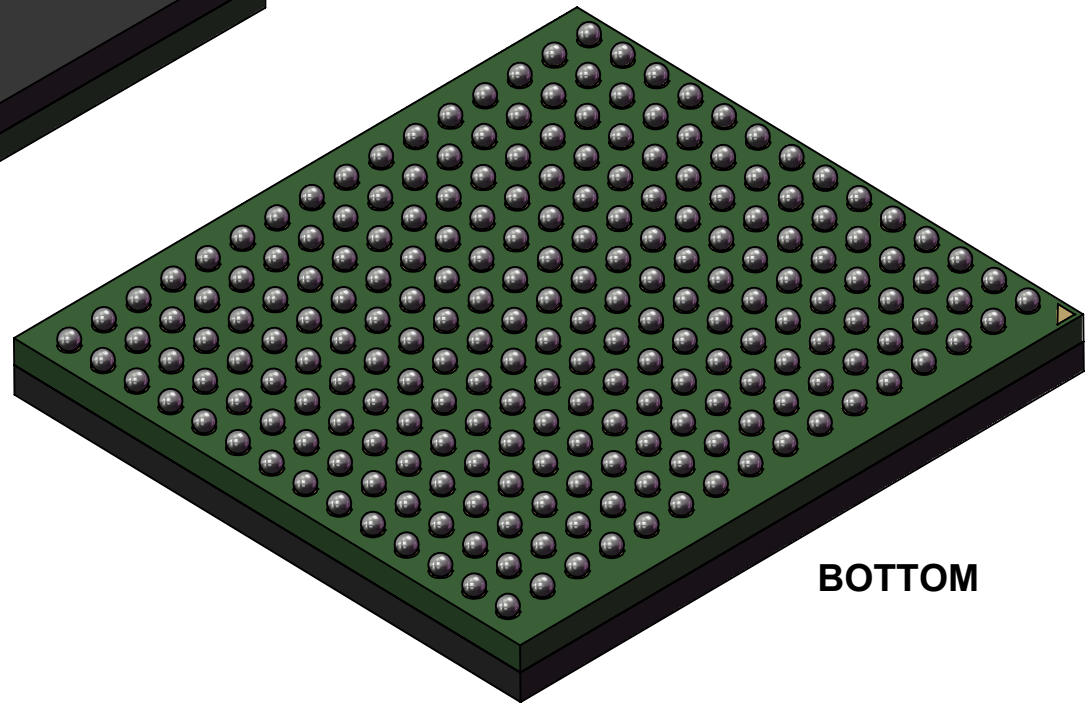
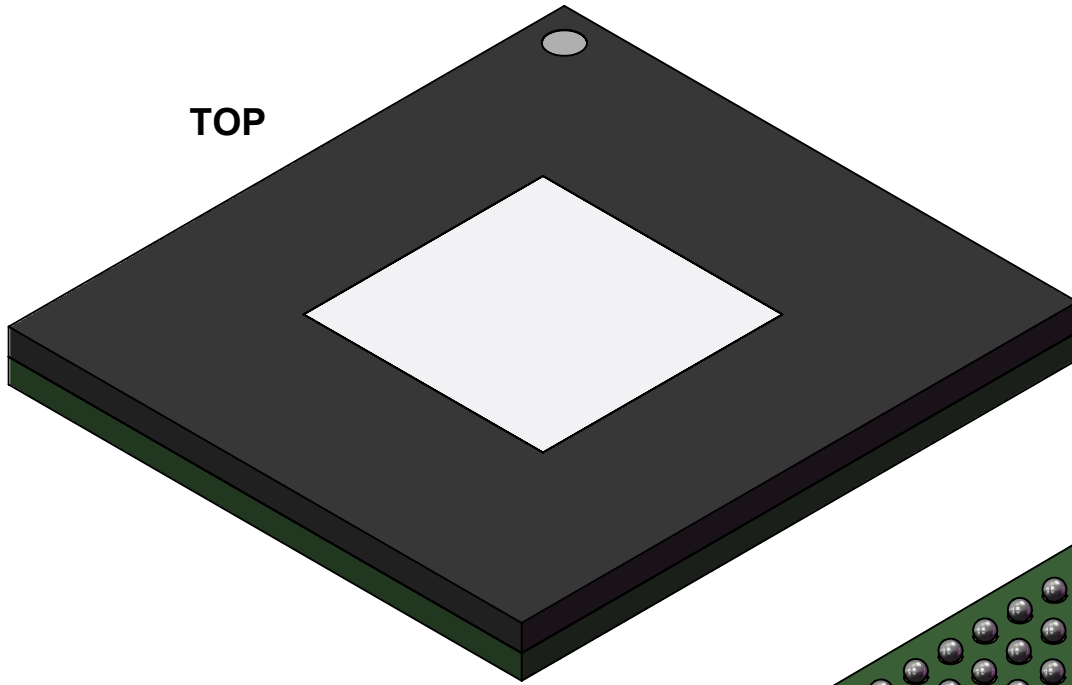
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER ϕ 0.40mm (16mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.150 [6mil].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING ϕ 0.33mm (13mil).

TopLine®			
TITLE		BGA224T.8C-14x16-D DUMMY BGA	
SCALE	SIZE	DRAWING NO.	REV
8:1	A	589141	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL

TOP



BOTTOM

TopLine[®]

TITLE BGA224T.8C-14x16-D
DUMMY BGA

SCALE 8:1	SIZE A	DRAWING NO. 589141	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3